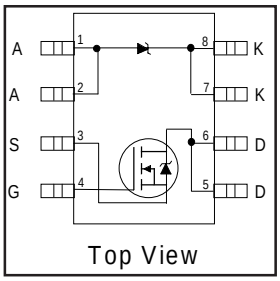
International
IOR Rectifier

IRF7353D1

FETKY™ MOSFET / Schottky Diode

- Co-packaged HEXFET® Power MOSFET and Schottky Diode
- Ideal For Buck Regulator Applications
- N-Channel HEXFET
- Low V_F Schottky Rectifier
- Generation 5 Technology
- SO-8 Footprint

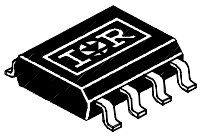


Top View

V_{DSS} = 30V

$R_{DS(on)}$ = 0.029Ω

Schottky Vf = 0.39V


SO-8

Description

The **FETKY** family of co-packaged MOSFETs and Schottky diodes offers the designer an innovative, board space saving solution for switching regulator and power management applications. Generation 5 HEXFET Power MOSFETs utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. Combinining this technology with International Rectifier's low forward drop Schottky rectifiers results in an extremely efficient device suitable for use in a wide variety of portable electronics applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics. The SO-8 package is designed for vapor phase, infrared or wave soldering techniques.

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter		Maximum	Units
I_D @ T_A = 25°C	Continuous Drain Current ④	6.5	A
I_D @ T_A = 70°C		5.2	
I_{DM}	Pulsed Drain Current ①	52	
P_D @T_A = 25°C	Power Dissipation ④	2.0	W
P_D @T_A = 70°C		1.3	
	Linear Derating Factor	16	mW/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
dv/dt	Peak Diode Recovery dv/dt ②	-5.0	V/ns
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Resistance Ratings

Parameter		Maximum	Units
$R_{\theta JA}$	Junction-to-Ambient ⑤	62.5	°C/W

Notes:

① Repetitive rating; pulse width limited by maximum junction temperature (see figure 9)

② Starting T_J = 25°C, L = 10mH, R_G = 25Ω, I_{AS} = 4.0A

③ I_{SD} ≤ 4.0A, di/dt ≤ 74A/µs, V_{DD} ≤ $V_{(BR)DSS}$, T_J ≤ 150°C

④ Pulse width ≤ 300µs; duty cycle ≤ 2%

⑤ Surface mounted on FR-4 board, t ≤ 10sec.

MOSFET Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	—	—	V	V_{GS} = 0V, I_D = 250µA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	0.023	0.032	Ω	V_{GS} = 10V, I_D = 5.8A ④
		—	0.032	0.046		V_{GS} = 4.5V, I_D = 4.7A ④
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	—	V	V_{DS} = V_{GS}, I_D = 250µA
g_{fs}	Forward Transconductance	—	14	—	S	V_{DS} = 24V, I_D = 5.8A
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	µA	V_{DS} = 24V, V_{GS} = 0V
		—	—	25		V_{DS} = 24V, V_{GS} = 0V, T_J = 55°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V_{GS} = -20V
Q_g	Total Gate Charge	—	22	33	nC	I_D = 5.8A
Q_{gs}	Gate-to-Source Charge	—	2.6	3.9		V_{DS} = 24V
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	6.4	9.6		V_{GS} = 10V (see figure 8) ④
$t_{d(on)}$	Turn-On Delay Time	—	8.1	12	ns	V_{DD} = 15V
t_r	Rise Time	—	8.9	13		I_D = 1.0A
$t_{d(off)}$	Turn-Off Delay Time	—	26	39		R_G = 6.0Ω
t_f	Fall Time	—	17	26		R_D = 15Ω ④
C_{iss}	Input Capacitance	—	650	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	320	—		V_{DS} = 25V
C_{rss}	Reverse Transfer Capacitance	—	130	—		f = 1.0MHz (see figure 7)

MOSFET Source-Drain Ratings and Characteristics

Parameter		Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.5	A	
I_{SM}	Pulsed Source Current (Body Diode)	—	—	30		
V_{SD}	Body Diode Forward Voltage	—	0.78	1.0	V	T_J = 25°C, I_S = 1.7A, V_{GS} = 0V
t_{rr}	Reverse Recovery Time (Body Diode)	—	45	68	ns	T_J = 25°C, I_F = 1.7A
Q_{rr}	Reverse Recovery Charge	—	58	87	nC	di/dt = 100A/µs ③

Schottky Diode Maximum Ratings

	Parameter	Max.	Units.	Conditions	
$I_{F(av)}$	Max. Average Forward Current	2.7	A	50% Duty Cycle. Rectangular Wave, T_A = 25°C	
		1.9		See Fig. 14	T_A = 70°C
I_{SM}	Max. peak one cycle Non-repetitive	120	A	5µs sine or 3µs Rect. pulse	Following any rated
	Surge current	11		10ms sine or 6ms Rect. pulse	load condition & with V_{RRM} applied

Schottky Diode Electrical Specifications

	Parameter	Max.	Units	Conditions	
V_{FM}	Max. Forward voltage drop	0.50	V	I_F = 1.0A, T_J = 25°C	
		0.62		I_F = 2.0A, T_J = 25°C	
		0.39		I_F = 1.0A, T_J = 125°C	
		0.57		I_F = 2.0A, T_J = 125°C .	
I_{RM}	Max. Reverse Leakage current	0.06	mA	V_R = 30V	T_J = 25°C
		16			T_J = 125°C
C_t	Max. Junction Capacitance	92	pF	V_R = 5Vdc (100kHz to 1 MHz) 25°C	
dv/dt	Max. Voltage Rate of Charge	3600	V/ µs	Rated V_R	

Power Mosfet Characteristics

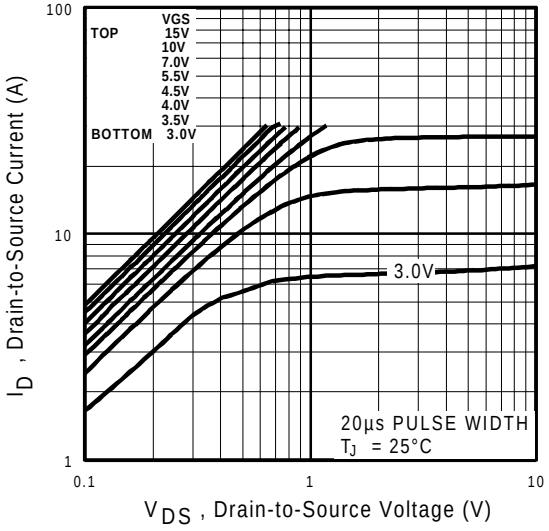


Fig 1. Typical Output Characteristics

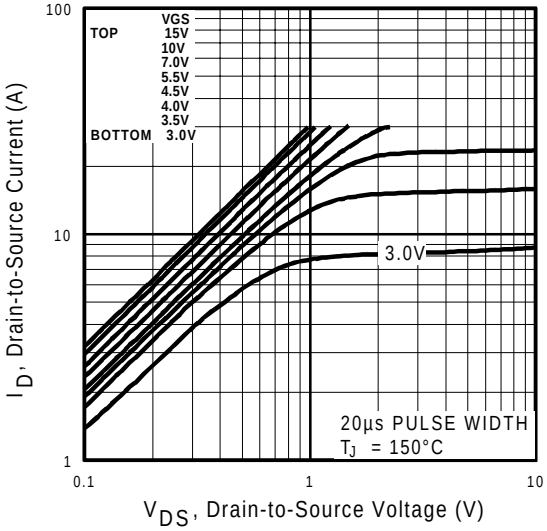


Fig 2. Typical Output Characteristics

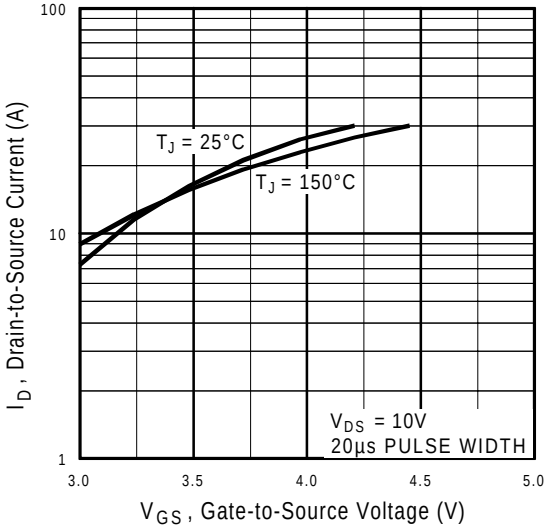


Fig 3. Typical Transfer Characteristics

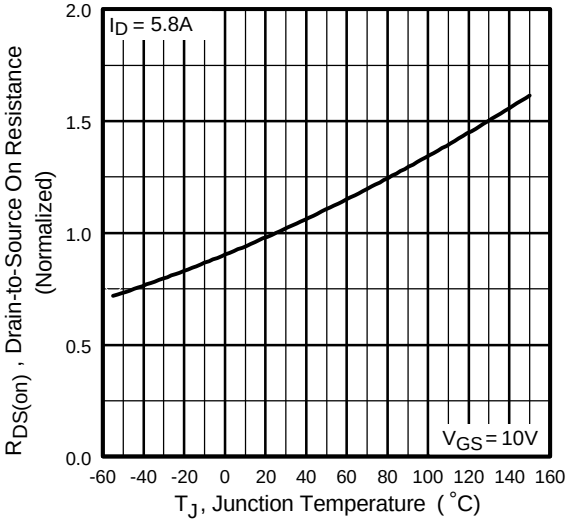


Fig 4. Normalized On-Resistance Vs. Temperature

Power Mosfet Characteristics

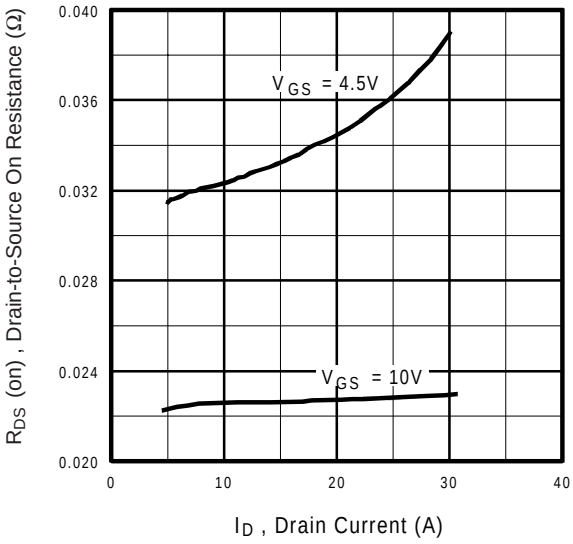


Fig 5. Typical On-Resistance Vs. Drain Current

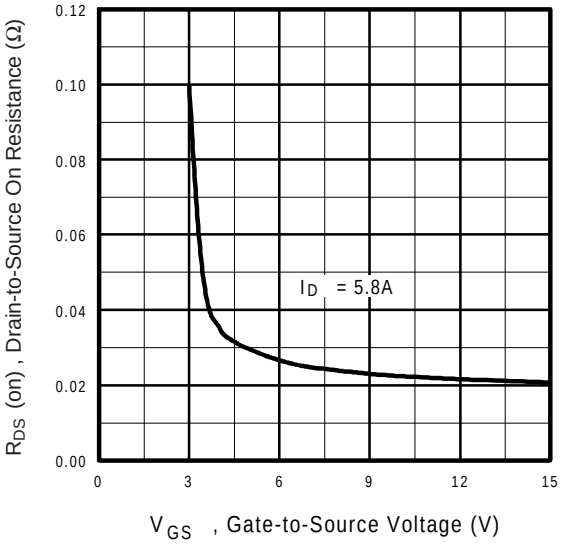


Fig 6. Typical On-Resistance Vs. Gate Voltage

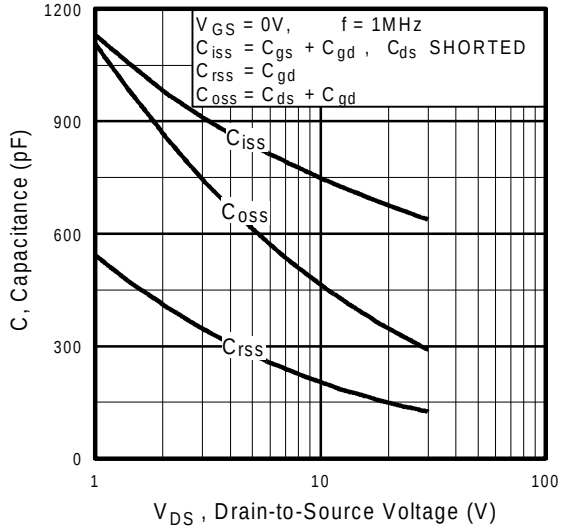


Fig 7. Typical Capacitance Vs. Drain-to-Source Voltage

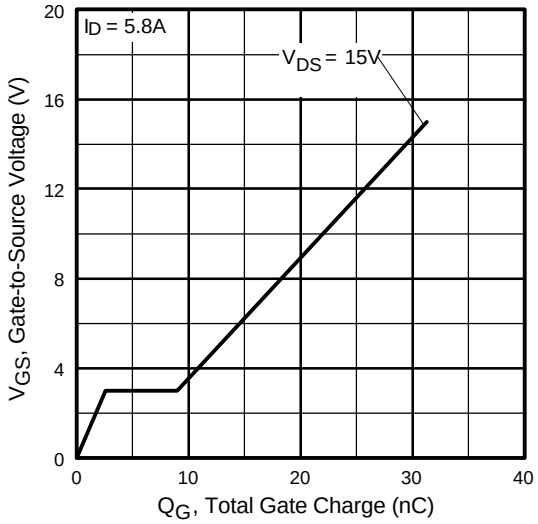


Fig 8. Typical Gate Charge Vs. Gate-to-Source Voltage

Power Mosfet Characteristics

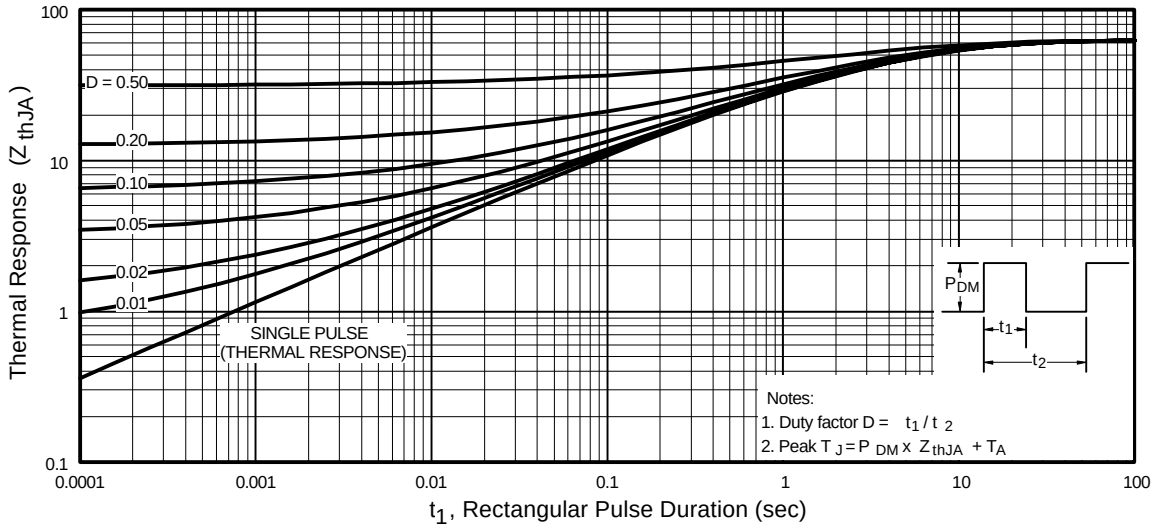


Fig 9. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

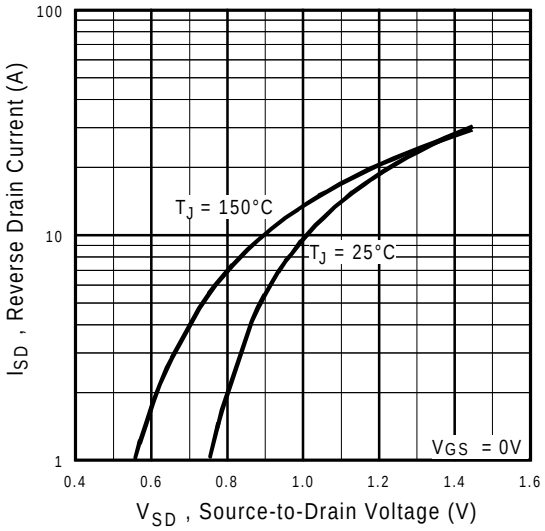


Fig 10. Typical Source-Drain Diode Forward Voltage

Schottky Diode Characteristics

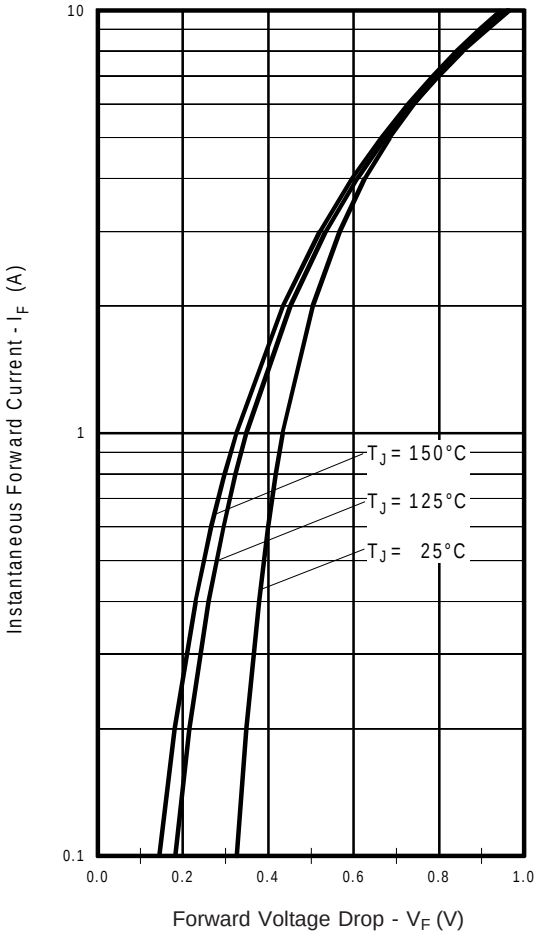


Fig. 12 -Typical Forward Voltage Drop Characteristics

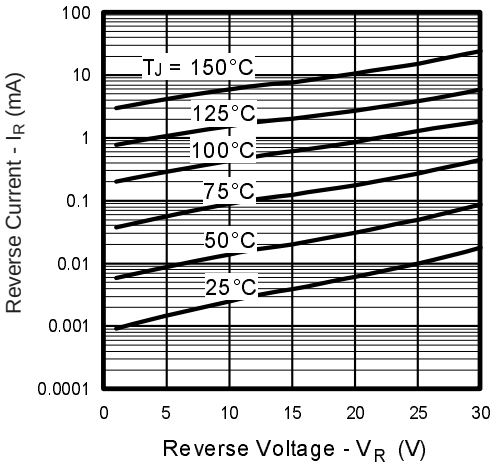


Fig. 13 - Typical Values of Reverse Current Vs. Reverse Voltage

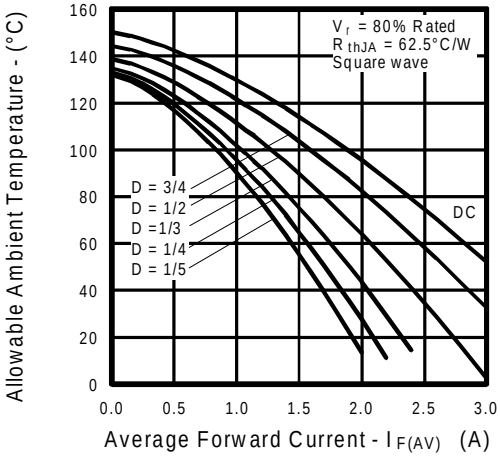
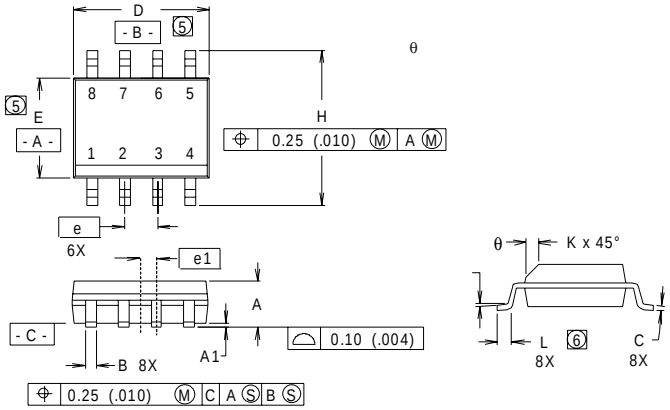


Fig.14 - Maximum Allowable Ambient Temp. Vs. Forward Current

SO-8 Package Details

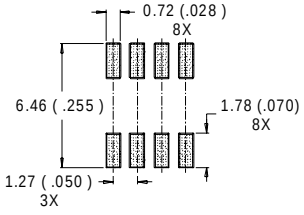


DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
θ	0°	8°	0°	8°

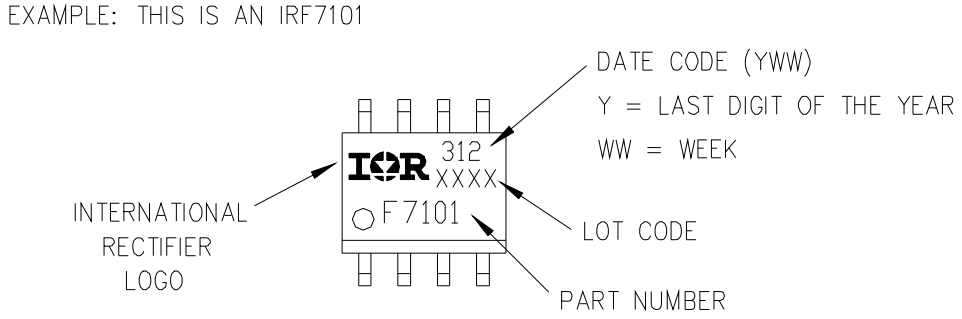
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS
   MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

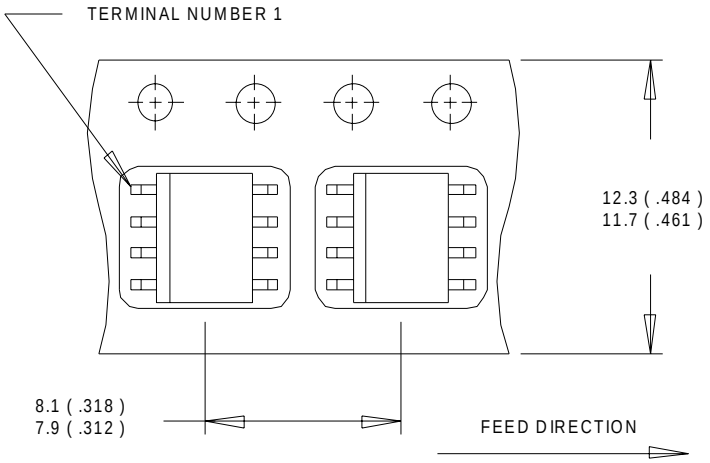
RECOMMENDED FOOTPRINT



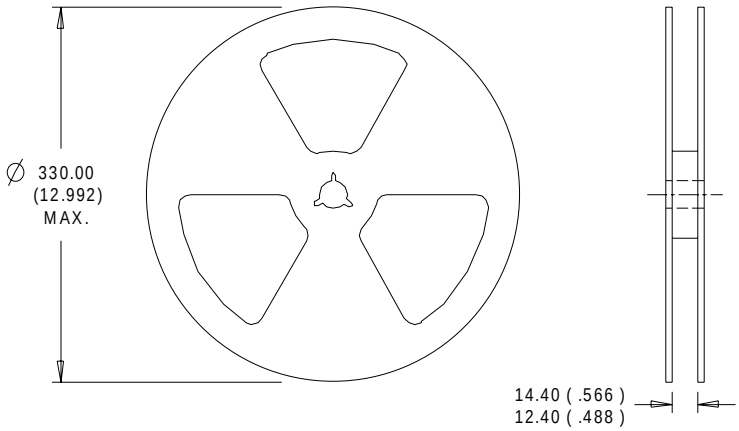
Part Marking



Tape and Reel



NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

International
IOR Rectifier

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